

Air-Cooled Thermal Management Solutions



SPECIALISTS IN POWER ELECTRONIC COMPONENTS AND ASSEMBLIES

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C&H Technology, Inc.

Introduction

C&H Technology - Air Cooled Thermal Solutions

Today's power electronic applications require thermal management solutions early in the design to support the higher switching frequencies and increasing power densities. C&H Technology engineers are available to assist and help choose a heatsink for your system or application. Our thermal solutions include extruded and bonded fin heat sinks, as well as a variety of liquid chilling solutions.

The thermal management of air cooled systems tends to be less costly in comparison to liquid cooled systems. Our extruded heatsink profiles have been handpicked from common shapes in the industry and are customizable to fit specific applications. These heat sinks come in several shapes and sizes with varying surface area perimeters, weights, and thermal performance ratings. Furthermore, our extruded heat sinks are cut to your desired length with the options of drilling & tapping of holes, flycut for surface flatness, plating, and more.

When space is at a premium, our selection of bonded fin heat sinks offer low thermal resistances at a fraction of the size. Additional customizations include mounting feet, baffle plates, and single, double, or triple fans based on selected model complete with a fan shroud.

Standard Materials

Heat Sink Extrusions:	Bonded Fin Heat Sinks:
Aluminum 6063	Base Plates: Aluminum 6063-T5 or 6061-T5
Aluminum C57B-T5	Fins: Aluminum 1100-H14, 3003 or 6061

Standard Tolerances

Flatness: 0.001 in/in	Place V	alues:	Finishes:
Roughness: #63 or better Saw Cut: <u>+</u> 0.020 Cut to Width: <u>+</u> 0.010 in	X .X .XX .XXX	± .1 ± .05 ± .01 ± .005	Natural Finish Clear Alodine 5200 - RoHS Compliant Clear Anodized – MIL-A-8625, Type II Black Anodized – MIL-A-8265, Type II Gold Iridite – MIL-C-5441, Type III Clear Chromate – MIL-C-5441 Type II Trivalent Chromate – RoHS Compliant

MIL-DTL-5541F

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Model	Perimeter	Width	Height	Weight	Thermal Resistance	Device Type	Assembly	Page Number
	(111-7111)	()	()	(105/11)	(°C/W/3in.)		TTUINE	Number
CHEH0011	105.000	9.80	2.850	12.81	0.710	Puk	Profile G	9
CHEH0012	98.070	6.96	2.670	9.50	0.700	Module		9
CHEH0017	85.140	7.00	3.130	7.84	0.800	Puk	Profile F	8
CHEH0023	71.250	4.75	4.500	4.33	1.000	Stud		7
CHEH0031	118.250	9.25	6.750	9.60	0.400	Stud		10
CHEH0032	48.100	4.75	2.625	2.50	1.500	Stud		5
CHEH0051	108.400	9.80	2.920	11.10	0.700	Puk		9
CHEH0055	72.000	4.48	2.270	4.32	1.050	Module		7
CHEH0057	158.710	6.80	3.035	10.05	0.480	Module		10
CHEH0073	91.690	4.96	5.380	9.11	0.820	Module		8
CHEH0077	185.000	6.38	3.420	8.86	0.085*	Module		11
CHEH0078	137.000	12.58	3.250	23.75	0.550	Puk	Profile H	10
CHEH0090	61.850	5.99	1.107	3.51	1.220	Module		7
CHEH0091	167.130	6.46	2.145	7.29	0.094*	Module		11
CHEH0332	12.620	2.13	0.687	0.78	4.400	Discrete		3
CHEH0711	31.080	4.75	1.250	1.42	1.900	Stud		3
CHEH0746	78.580	9.88	1.312	6.22	0.900	Module		7
CHEH0871	39.340	4.50	1.400	2.37	1.500	Module		4
CHEH0930	27.720	3.25	1.000	1.42	1.800	Module		3
CHEH1246	41.460	4.47	1.812	3.94	1.300	Module		5
CHEH1484	55.500	4.25	4.300	3.01	1.000	Stud		6
CHEH1806	36.060	4.13	1.310	2.71	1.500	Module		3
CHEH1822	37.890	4.13	1.750	2.92	1.400	Module		4
CHEH1842	56.870	6.75	1.631	4.32	1.000	Module		6
CHEH1912	51.268	4.20	2.465	5.78	1.100	Module		5
CHEH1916	59.340	8.68	1.470	4.50	1.000	Module		6
CHEH2056	53.250	8.37	1.312	4.25	1.100	Module		5
CHEH3040	22.560	3.93	0.590	1.41	2.300	Module		3
CHEH3286	87.390	6.05	1.650	5.84	0.800	Module		8
CHEH3334	39.180	5.80	1.050	3.35	1.300	Module		4
CHEH3399	80.450	7.89	1.080	4.33	0.900	Module		7
CHEH3415	131.020	8.00	1.630	6.15	0.800	Module		10
CHEH3442	38.510	5.29	1.332	3.47	1.400	Module		4
CHEH3490	38.970	5.39	1.050	2.98	1.500	Module		4
CHEH3515	24.470	2.12	1.015	1.43	2.700	Discrete		3
CHEH3589	50.636	3.01	1.015	1.39	2.300	Module		5
CHEH3598	94.249	5.93	1.220	4.15	0.900	Module		8
CHEH3603	85.901	9.88	2.930	7.86	1.300	Module		8
CHEH3647	38.490	2.40	1.650	1.56	1.300	Discrete		4
CHEH3648	58.770	5.00	1.650	3.30	1.000	Module		6
CHEH3671	215.115	10.00	2.920	13.25	0.350	Module		11
CHEH3702	141.970	17.00	1.332	11.04	0.490	Module		10
CHEH3728	118.070	6.65	3.170	6.40	1.060	Module		10
CHEH3896	78.378	7.20	2.480	5.45	1.400	Module		7
CHEH3969	55.940	6.25	2.000	3.44	1.400	Stud		6
CHEH3973	97.846	9.75	2.000	7.55	1.400	Module		8
CHEH3975	102.191	12.75	1.350	9.10	1.000	Module		9
CHEH4025	101.500	10.16	1.876	6.60	0.670	Module		9
CHEH13450	49.570	5.00	2.250	4.30	1.400	Puk	Profile D	5
CHEHK1750-12	N/A	5.06	2.060	N/A	0.190*	Stud		11
CHEHK18	100.400	4.92	5.310	11.80	0.700	Module	Profile A	9
CHEHK7	58.200	5.13	2.000	6.40	1.200	Puk	Profile E	6

* Thermal Performances based on forced airflow of 500LFM in units of °C/W/6in.





































* Thermal Performances based on forced airflow of 500 LFM



Thermal Management Bonded Fin Heat Sinks

NATURAL CONVECTION MODELS

Ideal for applications where forced air-cooling is not an option. While maintaining a similar thermal resistance, natural convection bonded fin heat sinks require half the amount of space as extruded heat sinks. Custom designs are available upon request.



NATURAL CONVECTION SPECIFICATIONS				
MODEL #	CH5111	CH5112	CH5113	CH5114
Dimension A	7.00"	11.81"	7.00"	11.81"
Dimension B	2.50"	5.00"	2.50"	5.00"
Flanges	None	None	1" Wide	1" Wide
Thermal Resistance	0.30°C/W	0.22°C/W	0.30°C/W	0.22°C/W

Information printed in this section has been developed by dimensioning for general applications. C&H Technology is prepared to provide assistance on all Engineered Heat Sinks by utilizing computer software designed specifically for this type of Heat Sink.



Thermal Management Bonded Fin Heat Sinks

FORCED CONVECTION - SINGLE FAN MODELS

Increased thermal performance over natural convection bonded fin heat sinks. Ideal for applications where high thermal density semiconductors, such as Power MOSFETs and IGBTs, are used. Models available fully equipped with a ball-bearing fan. Custom designs are available upon request.



FORCED AIR CONVECTION - SINGLE FAN MODELS				
MODEL #	CH5115	CH5116		
Dimension A	7.00"	11.81"		
Dimension B	9.50"	14.50"		
Dimension C	3.75"	6.25"		
Thermal Resistance	0.08°C/W	0.06°C/W		

Thermal performances based on 100 CFM fan. Mounting pattern shown fits standard "muffin" fans.



Thermal Management Bonded Fin Heat Sinks

FORCED CONVECTION - DOUBLE FAN MODELS

Ideal for designs with large IGBT, Diode, and SCR modules in high wattage applications. Exceptional thermal performances as low as 0.024°C/W – more effective cooling per cubic inch compared to extruded heat sinks. Models available fully equipped with ball-bearing fans. Custom designs are available upon request.



FORCED AIR CONVECTION - DOUBLE FAN MODELS				
MODEL #	CH5117	CH5118	CH5119	
Dimension A	11.81"	14.00"	16.00"	
Dimension B	14.59"	16.59"	18.59"	
Dimension C	6.00"	7.00"	8.00"	
Thermal Resistance	0.028°C/W	0.025°C/W	0.024°C/W	

Thermal performances based on 100 CFM fan. Mounting pattern shown fits standard "muffin" fans.



Thermal Management

Bonded Fin Heat Sinks

FORCED CONVECTION - TRIPLE FAN MODELS

Triple fan forced convection heat sinks have the highest watt per cubic inch performance over other bonded fin heat sink designs. Semiconductor modules can be mounted parallel to the heat sink fins to eliminate upstream heating effect. This allows for multiple IGBTs, Diodes and SCRs to operate at the same temperature and increase system reliability. Models available fully equipped with ball-bearing fans. *Custom designs are available upon request*.



FORCED AIR CONVECTION - TRIPLE FAN MODELS				
MODEL #	CH5120	CH5121	CH5122	
Dimension A	11.81"	14.00"	16.00"	
Dimension B	14.59"	16.59"	18.59"	
Dimension C	6.00"	7.00"	8.00"	
Thermal Resistance	0.02°C/W	0.019°C/W	0.0175°C/W	

Thermal performances based on 600 LFM fan. Mounting pattern shown fits standard "muffin" fans.



IMPINGEMENT HEAT SINK

Ideal for IGBT and power MOSFET applications as well as Diode and SCR bridges. The impingement cooling allows modules to be mounted close together while keeping an extremely low cost per watt. This results in all modules in a system to operate at the same temperature increasing system reliability. Additionally, the close mounting structure allows for shorter bus bars that reduces cost and lowers circuit inductance. The impingement style heat sinks provide very high performance cooling in a small package. Custom designs are available upon request.



IMPINGEMENT HEAT SINK MODELS				
MODEL #	CH6500	CH6600		
Dimension X	5.00"	8.00"		
Thermal Resistance	0.10°C/W	0.08°C/W		

Thermal performances based on 100 CFM fan. Mounting pattern shown fits standard "muffin" fans.



Our Partners for Power Electronics:







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